



INDIAN INSTITUTE OF TECHNOLOGY BOMBAY
MATERIALS MANAGEMENT DIVISION
Powai, Mumbai 400076.

Ref. PR No. 1000050164

Rfx. No. 6100002542

Benchtop Vacuum sintering System - Qty 1 No.
Technical Specification

| Sr. No | Item Description | Detailed Technical Specification | Technical Compliance (Yes / No) | Additional Information (if any) |
|--------|--------------------------------------------------------------------------------------------------------------------------|----------------------------------|---------------------------------|---------------------------------|
| 1. | Maximum temperature: | Upto 350 °C | | |
| 2. | Maximum clamping force: | >60 kN | | |
| 3. | Maximum sintering pressure: | >25 MPa | | |
| 4. | Process area diameter: | >60 mm | | |
| 5. | Should be compatible with silver and copper sintering of power semiconductor dies with typical dimensions of 4 mm x 6 mm | | | |
| 6. | Should be compatible with multi-chip and multi-layer sintering (in one step) | | | |
| 7. | Should be compatible with controlled environment (Vacuum, Nitrogen, formic acid) process to reduce surface oxidation | | | |
| 8. | Compatible with die attach to substrate and lead frame and substrate to baseplate | | | |
| 9. | Warranty: 1 Year | | | |
| 10. | Product Catalogues / Technical datasheet | | | |

Additional Requirement:

1. 5 years of Past Experience Required for same/ similar supply of equipment. Copies of minimum 2 purchase orders to be submitted along with the bid in support of having supplied the material.
2. The bidder should have service centre in India. The details of the same to be provided along with supporting documents.
3. The bidder should have average turnover of INR 1 crore during the last 3 financial year. Submit the Audited financial statements for the same.
4. Training should be provided to the concerned staff at the time of installation.
5. The material should be delivered within 5 months.